

<b>Product Class</b>	<b>PTC Level Sensors, housing types B590x0D*</b>
<b>Date</b>	<b>14.10.2019</b>
IMDS ID if available	
<b>Version</b>	<b>5.04</b>

Product Part (IMDS: semi component)	Material Class (IMDS: Material)	Material (Classification) VDA 231	Substance	TMPS**) [wt%]	CAS if applicable	typical mass of material [wt-%]	Traces see 1)
<b>Active Part</b>	Ceramic	3B	Ba-titanates Pb-titanates Sr-titanates Ca-titanates Dopants*)	69 15 10 5 1	12047-27-7 12060-00-3 12060-59-2 12049-50-2	1.065	
<b>Termination</b>	Noble Metal	1D7	Ag	100	7440-22-4	0.26	
	Heavy Metal	1C14	Ni	100	7440-02-0	0.13	
	Heavy Metal	1C2	Cr	100	7440-47-3	0.065	
<b>Solder</b>	Heavy Metal	1C15	Pb +)	97.5	7439-92-1	5.3	
			Sn	1	7440-31-5		
			Ag	1.5	7440-22-4		
<b>Leads</b>	Heavy Metal	1C14	Ni	97	7440-02-0	23.2	
			Ag	3	7440-22-4		
	Thermoplastic	2A	PTFE insulation	100	9002-84-0	17.1	
<b>Housing</b>	Iron & Steel incl. Alloys	1A	Stainless Steel X5CrNi18-10	100		39.08	
<b>Potting compound</b>	Duromer	2D	Epoxy	65		10.31	
			Mica	30	12001-26-2		
			Silica others*)	2 3	14808-60-7		
	Organic, solid	4B	Silicone rubber	100		3.49	
<b>Sum of total</b>						<b>100</b>	

<b>sizes [mm]</b>	<b>weight range [ g ]</b>	<b>material numbers</b>	<b>sizes [mm]</b>	<b>weight range [ g ]</b>	<b>material numbers</b>
2,8 x 2,8 x 82	0,63	B59050D1*	2,8 x 2,8 x 63,5	0,6	B59030D1*
<b>Not part of a Product Class</b>					

<b>Contact</b>	Ronner Christoph	<b>Important remarks:</b> 1) The declaration limit is 0.1% as defined by IEC 62474 (IEC PAS 61906). Traces are product parts, substances etc. that are below a percentage of 0.1 % by weight, if not otherwise regulated. 2) This Material Data Sheet contains typical values of the respective products set forth herein. We expressly point out that all values and statements contained herein are based on our best present knowledge and cannot be regarded as binding statements or binding product specifications, unless otherwise explicitly agreed in writing. TDK ELECTRONICS AG AND ITS AFFILIATES HEREBY EXPRESSLY DISCLAIM ANY REPRESENTATION OR WARRANTY, WHETHER EXPRESS, IMPLIED OR STATUTORY, WITH REGARD TO THE STATEMENTS AND VALUES CONTAINED HEREIN, INCLUDING BUT NOT LIMITED TO ANY REPRESENTATION OR WARRANTY OF MERCHANTABILITY OR SUITABILITY FOR ANY PURPOSE.
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*) others: (not declarable or prohibited substances acc. GADSL) **) typical mass percentage of substance  +) listed in the Candidate list of Substances of Very High Concern acc. to Regulation 1907/2006/EC		

**The products set forth herein are "RoHS-compatible".** RoHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8<sup>th</sup>, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

**RoHS - Exemptions for the Product Class / Product according to Annex III:** (  valid  not valid )

- no exemptions;
- Exemption 6 (a): Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35 % lead by weight;
- Exemption 6 (b): Lead as an alloying element in aluminium containing up to 0,4 % lead by weight;
- Exemption 6 (c): Copper alloy containing up to 4 % lead by weight;
- Exemption 7 (a): Lead in high melting temperature type solder (i.e. lead-based alloys containing 85 % by weight or more lead);
- Exemption 7 (c)-I: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound;
- Exemption 7 (c)-II: Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher;
- Exemption 7 (c)-III: Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC;
- Exemption 15: Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages;
- Other Exemption than above .....